WHAT IS CLAIMED IS:

1. A laminated component for use in manufacturing articles such as printed circuit boards, said component comprising:

a separator having first and second surfaces;

a conductive film layer disposed against said first surface of said separator; and

a non-conductive film layer disposed against said second surface of said separator.

2. A laminated component for use in manufacturing articles such as printed circuit boards, said component comprising:

a separator having first and second surfaces;

a conductive film layer positioned on said first surface of said separator, said conductive film layer having larger lateral dimensions than said separator such that a portion of said conductive film layer extends beyond said separator; and

a non-conductive film layer positioned on said second surface of said separator, said non-conductive film layer having larger lateral dimensions than said separator such that a portion of said non-conductive film layer extends beyond said separator, wherein said extending portion of said conductive film layer and said extending portion of said non-conductive film layer are joined together.

3. The component of claim 2 wherein said extending portion of said conductive film layer and said extending portion of said non-conductive film layer are joined together by adhesive.

4. The component of claim 2 wherein said extending portion of said conductive film layer and said extending portion of said non-conductive film layer are joined together at the peripheries of said conductive film layer and said non-conductive film layer.

5. The component of claim 2 wherein said separator is made of aluminum.

6. The component of claim 5 wherein said separator has a thickness of about 254 and 762 microns.

7. The component of claim 2 wherein said conductive film layer is made of copper.

8. The component of claim 2 wherein said non-conductive film layer is made of a material selected from the group consisting of aluminum, polytetrafluoroethylene and silicone.

9. A laminated component for use in manufacturing articles such as printed circuit boards, said component comprising:

a conductive film layer having a band of adhesive disposed on a first surface thereof so as to define an enclosed central area inwardly thereof;

a separator placed on said first surface of said conductive film layer within said central area; and

a non-conductive film layer positioned on said separator, said non-conductive film layer having larger lateral dimensions than said separator such that a portion of said non-conductive film layer extends beyond said separator, wherein said extending portion of said non-conductive film layer is pressed against said adhesive to form a joint between said conductive film layer and said non-conductive film layer.

10. The component of claim 9 wherein said joint joins said conductive film layer and said non-conductive film layer together at their peripheries.

11. The component of claim 9 wherein said joint seals said central area.

12. The component of claim 9 further comprising a space between said separator and said joint.

13. The component of claim 9 wherein said separator is made of aluminum.

14. The component of claim 13 wherein said separator has a thickness of about 254 and 762 microns.

15. The component of claim 9 wherein said conductive film layer is made of copper.

16. The component of claim 9 wherein said non-conductive film layer is made of a material selected from the group consisting of aluminum, polytetrafluoroethylene and silicone.

17. A method of making printed circuit boards, said method comprising:

providing laminated components, each laminated component comprising a separator having first and second surfaces, a conductive film layer disposed against said first surface of said separator, and a non-conductive film layer disposed against said second surface of said separator;

assembling a book including a first steel plate, a first laminated component placed on said first steel plate, a core assembly placed on said first laminated component, a second laminated component placed on said core assembly, and a second steel plate placed on said second laminated component, wherein each laminated component is arranged so that its conductive film layer abuts said core assembly and its non-conductive film layer abuts a corresponding one of said steel plates; and

subjecting said book to heat and pressure.

18. The method of claim 17 further comprising separating said non-conductive film layers and said separators from said conductive film layers after subjecting said book to heat and pressure.